Vishay



Thick Film Resistor Array



The CRA04S thick film resistor array is constructed on a high grade ceramic body with convex terminations. A small package enables the design of high density circuits. The single component reduces board space, component counts, and assembly costs.

FEATURES



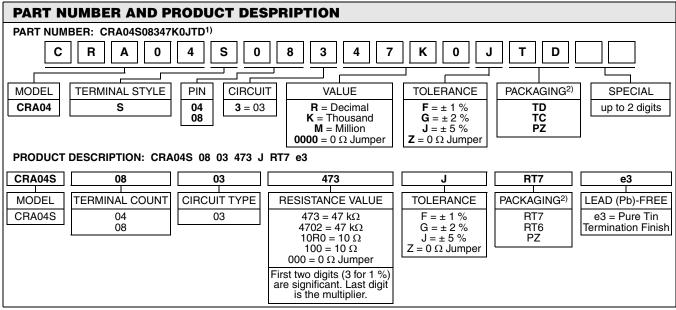
- · Convex terminal array with square corners
- Wide ohmic ramge: 10R to 1M0
- 4 or 8 terminal package with isolated resistors
- Lead (Pb)-free solder contacts on Ni barrier layer
- Pure tin plating provides compatibility with lead (Pb)-free and lead containing soldering processes
- Compatible with "Restriction of the use of Hazardous Substances" (RoHS) directive 2002/95/EC (issue 2004)

STANDARD ELECTRICAL SPECIFICATIONS								
MODEL	CIRCUIT	POWER RATING P _{70 °C} W	LIMITING ELEMENT VOLTAGE MAX. V≅	TEMPERATURE COEFFICIENT ppm/K	TOLERANCE %	$\begin{array}{c} \textbf{RESISTANCE} \\ \textbf{RANGE} \\ \Omega \end{array}$	E-SERIES	
	03	0.063	50	± 100	± 1	10R - 1M0	24 + 96	
CRA04S				± 200	± 2; ± 5	TON - TIVIO	24	
		Zero-Ohm-Resistor: $R_{\text{max}} \le 50 \text{ m}\Omega$, $I_{\text{max}} = 1 \text{ A}$						

TECHNICAL SPECIFICATIONS						
PARAMETER	UNIT	CRA04S				
Rated Dissipation at 70 °C ²⁾	W per element	0.063				
Limiting Element Voltage ¹⁾	V≅	50				
Insulation Voltage (1 min)	V _{dc/ac peak}	100				
Category Temperature Range	°C	- 55/+ 125 (+ 155)				
Insulation Resistance	Ω	> 10 ⁹				

Notes

- 1. Rated voltage: $\sqrt{P \times R}$
- 2. The power dissipation on the resistor generates a temperature rise against the local ambient, depending on the heat flow support of the printed-circuit board (thermal resistance). The rate dissipation applies only if the permitted film temperature of 155 °C is not exceeded.



Notes

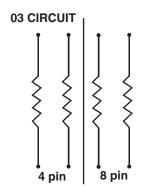
- 1. Preferred way for ordering products is by use of the PART NUMBER.
- 2. Please refer to the table PACKAGING, see next page.

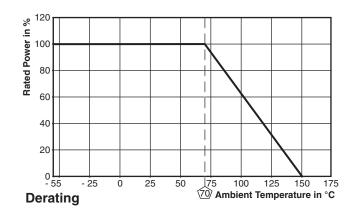


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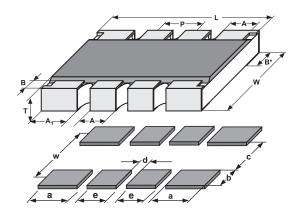
PACKAGING								
			PITCH	PIECES/REEL	PACKAGING CODE			
MODEL	TAPE WIDTH	DIAMETER			PAPER TAPE			
					PART NUMBER	PRODUCT DESCRIPTION		
		180 mm/7"	2 mm	10 000	TD	RT7		
CRA04S	8 mm	330 mm/13"	2 mm	20 000	TC	RT6		
		330 mm/13"	2 mm	50 000	PZ	PZ		

CIRCUIT





DIMENSIONS



PIN	DIMENSIONS [in millimeters]							
NO#	L	Α	A ₁	В	B*	P _{NOM}	T	W
4	1.0 ± 0.1	ı	0.33	0.15	0.25	0.65	0.35	1.0
8	2.0 ± 0.2	0.30	0.4	0.15	0.25	0.50	0.45	1.0
TOL	-	± 0.15	± 0.15	± 0.10	± 0.1	-	± 0.1	± 0.15

SOLDER PAD DIMENSIONS [in millimeters]							
	c w d a b e						
WAVE	0.45	1.0	0.2	0.4	0.5	0.3	

The dimensions shown are for a 8 pin part. For parts with different pin numbers use the same pitch and add or substract pads as required.

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TEST PROCEDURES AND REQUIREMENTS							
EN 60115-1							
TEST	CONDITIONS OF TEST	REQUIREMENTS PERMISSIBLE CHANGE $(\triangle R/R)^{1)}$					
(clause)	CONDITIONS OF TEST	STABILITY CLASS 1 OR BETTER	STABILITY CLASS 2 OR BETTER				
	stability for product types: CRA04S	10 Ω to 1 MΩ	10 Ω to 1 M Ω				
Resistance (4.5)	-	± 1 %	± 2 %; ± 5 %				
Temperature coefficient (4.8.4.2)	20/- 55/20 °C and 20/125/20 °C	± 100 ppm/K	± 200 ppm/K				
Overload (4.13)	$U = 2.5 \times (P_{70} \times R)^{1/2}$ $\leq 2 \times U_{\text{max}}; 0.5 \text{ s}$	± (0.25 % R + 0.05 Ω)	± (0.5 % R + 0.05 Ω)				
Solderability (4.17.5) ²⁾	Aging 4 h at 155 °C, dryheat Solder bath method; 235 °C; 2 s Visual examination	Good tinning (≥ 95 % covered) no visible damage					
Resistance to soldering heat (4.18.2)	Solder bath method; (260 ± 5) °C; (10 ± 1) s	± (0.25 % R + 0.05 Ω)	± (0.5 % R + 0.05 Ω)				
Rapid change of temperature (4.19)	30 min. at LCT = - 55 °C; 30 min. at UCT = 125 °C; 5 cycles	± (0.25 % R + 0.05 Ω)	$\pm (0.5 \% R + 0.05 \Omega)$				
Damp heat, steady state (4.24)	(40 ± 2) °C; 56 days; (93 ± 3) % RH	± (1 % R + 0.05 Ω)	± (2 % R + 0.1 Ω)				
Climatic sequence (4.23)	16 h at UCT = 125 °C; 1 cycle at 55 °C; 2 h at LCT = -55 °C; 1 h/1 kPa at 15 °C to 35 °C; 5 cycles at 55 °C U = (P ₇₀ x R) ^{1/2} U = U _{max} ; whichever is less severe	± (1 % R + 0.05 Ω)	± (2 % R + 0.1 Ω)				
Endurance at 70 °C (4.25.1)	$U = (P_{70} \times R)^{1/2}$ $U = U_{\text{max}}$; whichever is less severe 1.5 h on; 0.5 h off; 70 °C; 1000 h	± (1 % R + 0.05 Ω)	± (2 % R + 0.1 Ω)				
Extended endurance (4.25.1.8)	Duration extended to 8000 hours	± (2 % R + 0.1 Ω)	± (4 % R + 0.1 Ω)				
Endurance at upper category temperature (4.25.3)	UCT = 125 °C; 1000 h	± (1 % R + 0.05 Ω)	± (2 % R + 0.1 Ω)				

Notes

- 1. Figures are given for a single element.
- 2. Solderability is specified for 2 years after production or requalification. Permitted storage time is 20 years.

APPLICABLE SPECIFICATIONS

EN 60115-1 Generic Specification
 EN 140400 Sectional Specification
 EN 140401-802 Detail Specification

IEC 60068-2-X
 Variety of environmental test procedures

EIA 481 Packaging of SMD components

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Legal Disclaimer Notice



Vishay

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